

RoHS Compliance Material Declaration Report

Company:

Address:

Phone number:

Date:

Part Detail					
Pericom Part Number		Manufacturer part description	Package Type	Number of Pin/Terminal	Component overall weight (g)
PI4ULS3V16MNLE		Universal Bi-directionalLeve	VFPGA	45	0

RoHS Compliance		
Is Part compliant to EU RoHS Directive? [1] Yes, [2] Yes with tech exemption* [3] Yes but needs product application exemption* [4] No	RoHS tech exemption [2] details.	Date Component was RoHS Compliant.
Yes	N/A	Since Inception

Content of RoHS restricted materials (g)						
Lead	Cadmium	Mercury	Hexavalent Chromium	Polybrominated biphenyls (PBB)	Polybrominated Diphenylethers (PBDE)	RoHS restricted substance added intentionally? For what reason?
0	0	0	0	0	0	N/A

Component Soldering Process						
Interconnect Composition, (Metallurgy of the lead/terminal)	JEDEC JEDS97 Pb-free Category	Compatible with a 260C 10s Pb-Free assembly process	Backward compatible with SnPb assembly	Maximum Processing Temperature (°C)	Max Temperature Duration	Max Number of reflow cycles
Sn/Ag/Cu	e1	0	0	0	40	3

Plastics (if applicable)			
Oxygen Index	Type of plastic material used in the component	Fire: UL Rating	MSL Level (per JEDEC STD 020C)
>28%	Epoxy Resin	V-0	0

Tin (Sn) Plating (If Applicable)					
Tin (Sn) Plating – is it Matte (M) or Bright (B)?	Tin (Sn) Plating Thickness	Tin (Sn) plating is there a Nickel (Ni) Barrier? - Yes / No	Nickel Barrier Thickness	If no Nickel barrier is the tin (Sn) termination finish heat treated?	Performed Tin Whisker Test ?
0	0	0	0	0	0

Bismuth (Bi)
Bismuth (Bi) Content (if applicable)
0